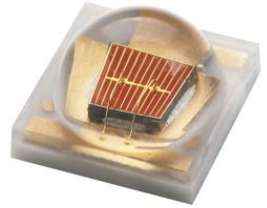


Part No: SEL-3535-R-2V350



Applications:

Bollards/Security/Garden/Architectural,etc

Features:

- Package: Al_2O_3 Ceramics molding package
- Chip technology:Vertical chip
- Emitting Color: Red
- Viewing Angle:120°
- Device Outline:3.45×3.45×2.20(mm)
- Typ.color coordinates : (625nm)
- Long operating life
- Never vulcanized
- HBM ESD:2000V
- MSL:2a
- Compliance with RoHS and REACH
- Pb-Free

1、Absolute maximum ratings:

Parameter	Symbol	Value	Unit
Power Dissipation	P_d	3	W
Forward Current	I_{Fm}	1000	mA
Surge Current ($t \leq 1\text{ms}$; $D=1/10$; $T_s=25\text{ }^\circ\text{C}$)	I_{Fs}	1100	mA
Reverse Voltage ($T_s=25\text{ }^\circ\text{C}$)	V_R	5	V
Operating Temperature	T_{opr}	- 40 ~ +100	$^\circ\text{C}$
Storage Temperature	T_{str}	- 40 ~ +100	$^\circ\text{C}$
Junction Temperature	T_j	130	$^\circ\text{C}$
HBM ESD	V_{ESD}	2	KV

2、Electrical and optical characteristics (T_s = 25°C) :

Parameter	Symbol	Test Condition	Value			Unit	
			Min.	Typ.	Max.		
Forward Current	IF	——	50	350	1000	mA	
Forward Voltage	VF	IF = 350mA	1.8	——	2.2	V	
Luminous Flux	Φ	IF = 350mA	40	60	80	lm	
Dominant Wavelength	λ d	IF =350mA	620	625	630	nm	
Viewing Angle	2 θ 1/2	IF = 350mA	——	120	——	Deg.	
Thermal Resistance (Junction to Solder)	Real	Rth JS real	IF = 350mA	——	4.0	——	K/W

Notes: Error: VF: ±0.10V, IV: ±8%, Other: ±5%

3、Product Ranks:

Brightness Grading (lm)

(Ta=25℃ ; IF=350mA)

Rank	Luminous Flux	Luminous Flux
	光通量 (min)	光通量 (max)
	40	60
	60	80

Notes: Brightness error: $\pm 8\%$

Voltage grading (V)

(Ta=25℃ ; IF=350mA)

Rank	Voltage	Voltage
	(min)	(max)
	1.8	2.2

Notes: Voltage error: $\pm 0.10V$

Wavelength Rank (nm)

(Ta=25℃ ; IF=350mA)

Rank	Wavelength	Wavelength
	(min)	(max)
	620	630

Notes: Wavelength error: $\pm 5\%$

4、Characteristics Graph:

Fig.1 Relative spectral curve

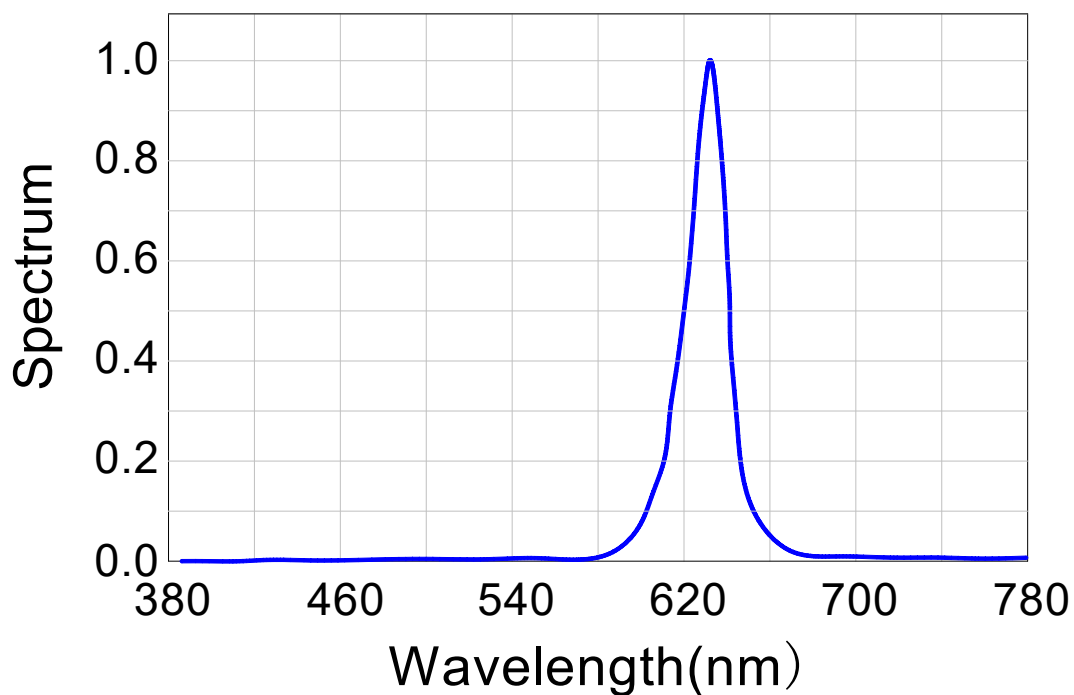


Fig.2 Radiation Characteristic

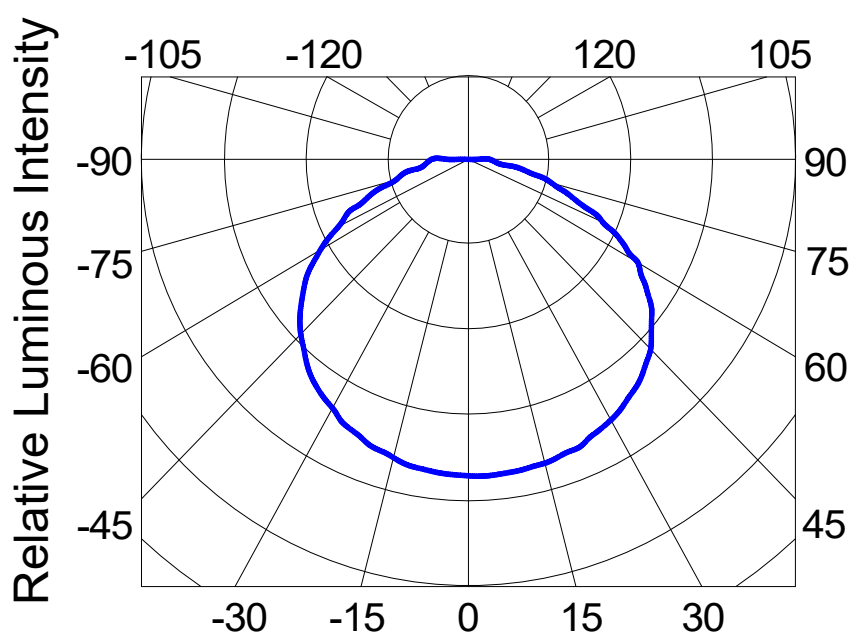


Fig.3 Forward Current vs. Forward Voltage

$$I_F = f(V_F); T_s = 25^\circ\text{C}$$

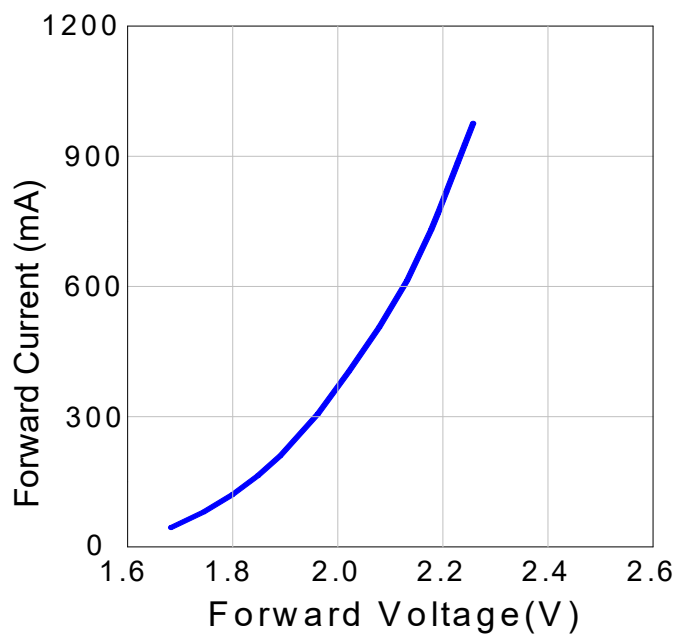


Fig.4 Relative Luminous Intensity vs. Forward Current

$$\Phi/\Phi(350\text{mA}) = f(I_F); T_s = 25^\circ\text{C}$$

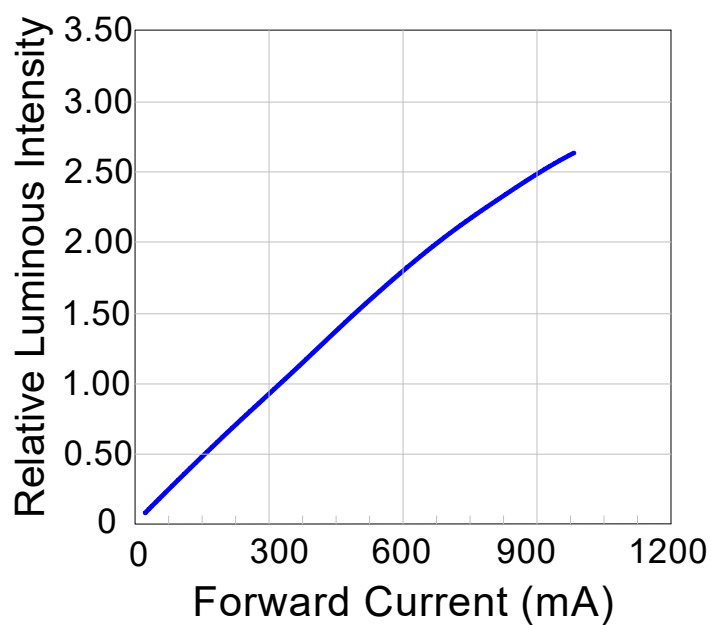


Fig.5 Max. Permissible Forward Current

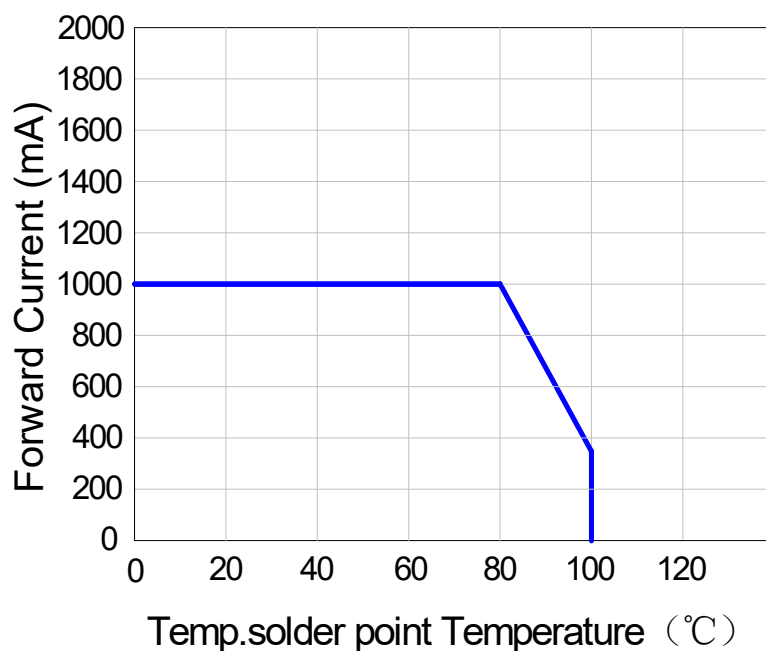
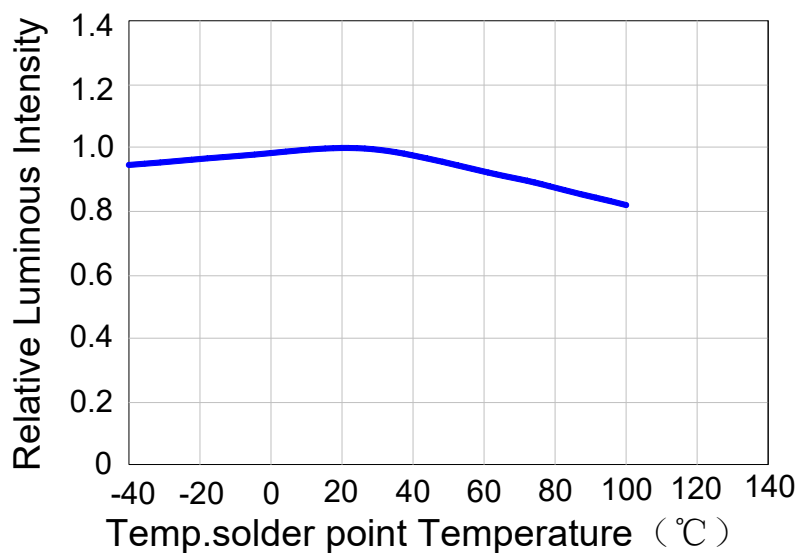
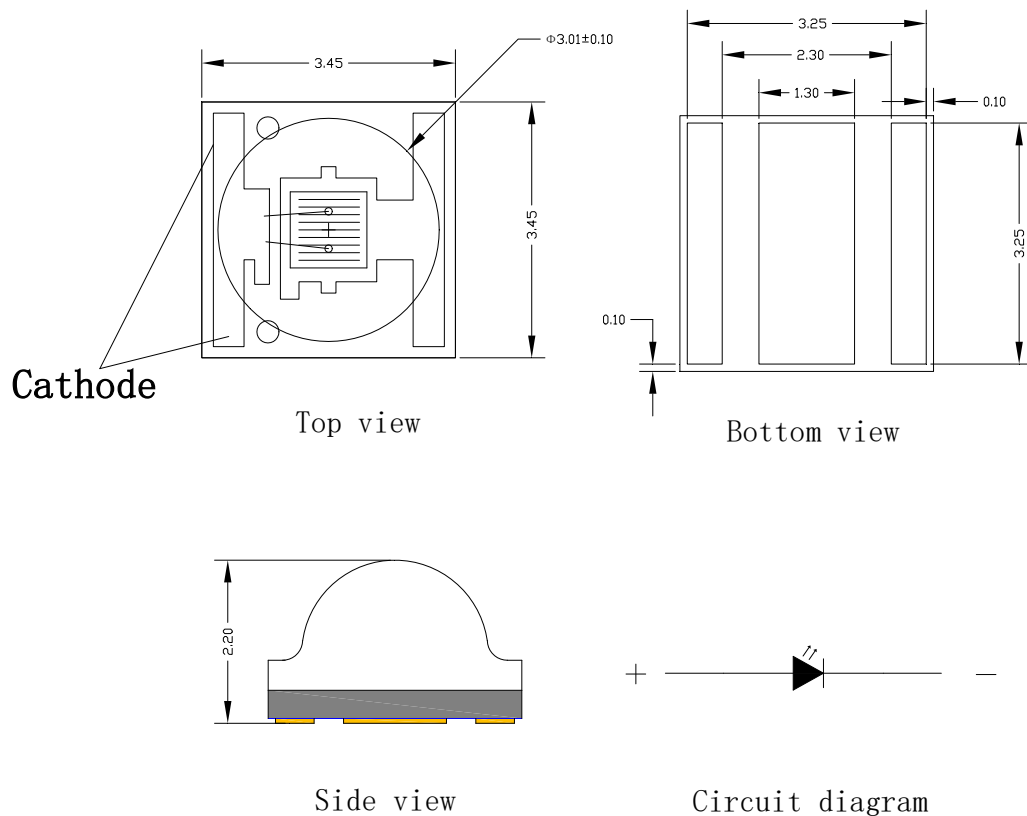


Fig.6 Relative Luminous Intensity vs. Temp.solder point Temperature

$$\Phi/\Phi(25^{\circ}\text{C})=f(T_s); I_F=350\text{mA}$$

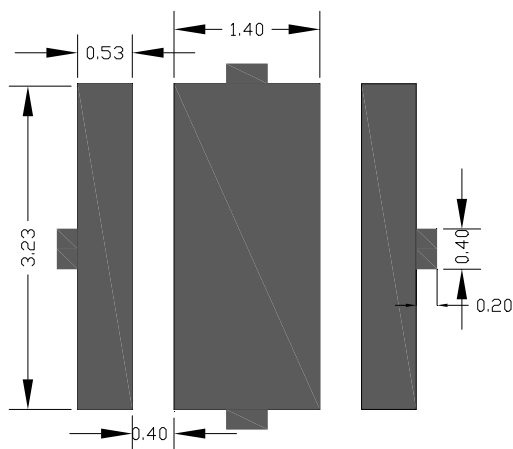


5、Outline Dimensions:



Notes: Tolerance is ± 0.1 mm

6、Reference Pad size:

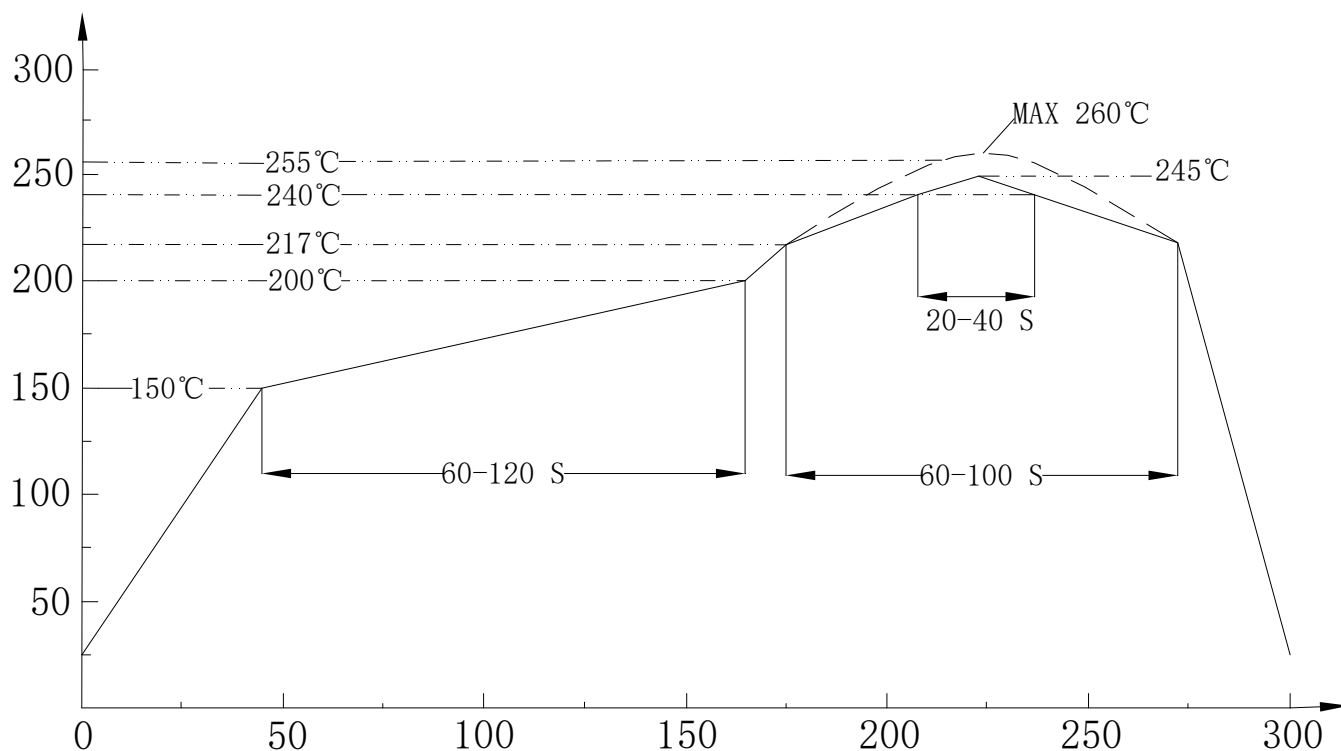


Notes:

- 1、Tolerance is ± 0.1 mm
- 2、For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere.
Package not suitable for ultra sonic cleaning.

7、Reflow curve

Product complies to MSL Level 2a. to JEDEC J-STD-020E



Curvilinear feature	Lead-free combination Recommended criteria	Uni
Average preheating heating rate 25 °C to 700 °C	2	°C/sec
Warm-up time	60-120	secs
Reflux temperature	217	°C
Reflux time	60-100	secs
Peak temperature(max))	260	°C
The time when the actual peak temperature is within 5 °C	20-40	secs
Cooling rate	4	°C/sec

Notes: Hand Soldering (Not Recommended)

8、Specification of Packing

8.1 Label Form Specification



No:
P/N: P35--627A0101-0301B0-B
IV code:
VF code:
λ/Tc code:
IF:
Lot No:
Cus No:



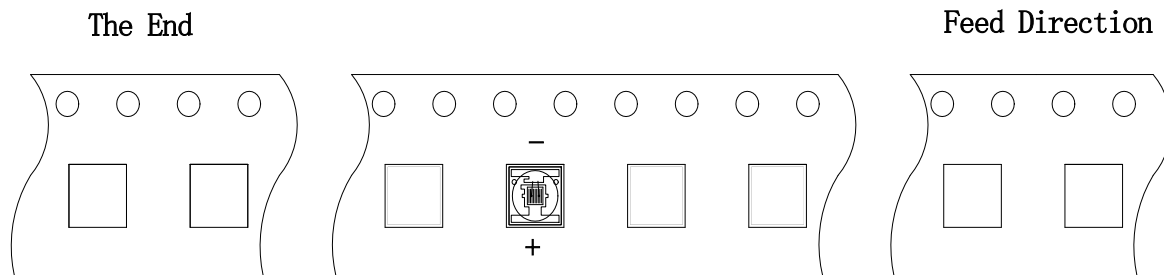
IV: 40-60lm
VF: 1.8-2.2V
λ/Tc : 620-630nm
Q'ty: 1000PCS
Date:

RoHS

QC

No: Product number	IV: Light intensity rank
P/N: Product name	VF: Voltage rank
IV code: Light intensity code	λ/Tc: Wavelength rank
VF code: Voltage code	Q'ty: package quantity
λ/Tc code: Wavelength code	Date: Print date
IF: Current	QC:
Lot No:	
Cus No: Customer number	

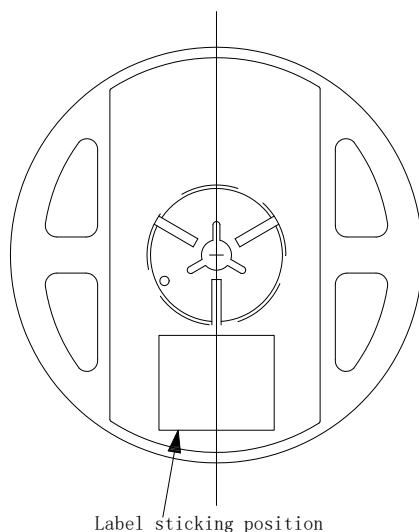
8.2 Taping and Orientation(Reel packing: 1000PCS)



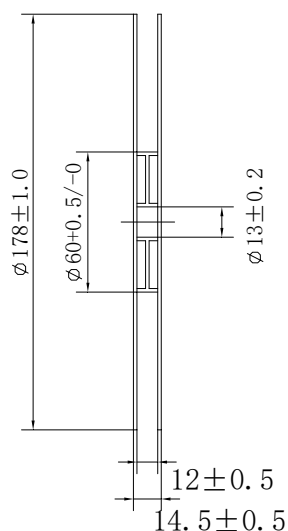
The blank space With 200mm

A roll of 1000PCS

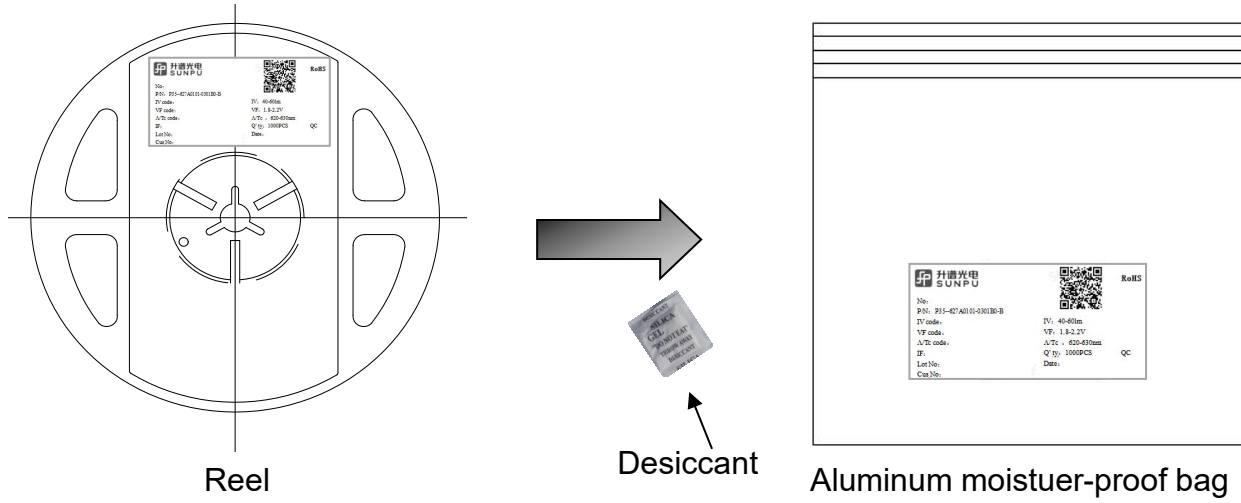
The blank space With 400mm



Label sticking position



8.3 Specification of Packing



Notes:

- ◆ Reel packing: 1000PCS
- ◆ humidity sensitive products packed in aluminum foil bags, containing desiccant.

9、Notes

- 9.1 Please note that the Light Board in the test, not live plug-in operation, to avoid the instant high current LED breakdown
- 9.2 To ensure the quality of our LEDs, So please do not put pressure on the LEDs. Do not fold, bend or squeeze LED devices
- 9.3 in order to ensure the reliability of LED, sealed packaging is recommended for semi-finished products or module components that have been pasted during circulation, transportation and storage.
- 9.4 To ensure the reliability of LED, please complete one time welding, not too many reflow soldering, otherwise on the bead will have a destructive impact. Repair should not be done after the LEDs have been soldered.

10、Revision History

Rev	Revision time	Revisions
A/1	2025/07/04	New version